

Quad 2-Input AND Gate

High-Performance Silicon-Gate CMOS

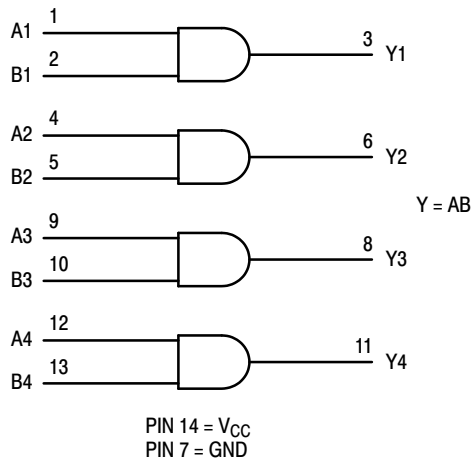
MC74HC08A, MC74HCT08A

The MC74HC08A/MC74HCT08A is identical in pinout to the LS08. The MC74HC08A device inputs are compatible with Standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs. The MC74HCT08A inputs are compatible with Standard CMOS or TTL outputs.

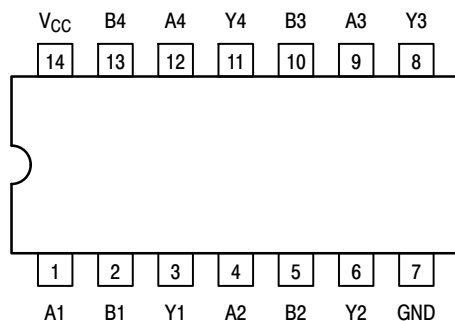
Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 2.0 to 6.0 V (HC), 4.5 to 5.5 V (HCT)
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance With the JEDEC Standard No. 7A Requirements
- Chip Complexity: 24 FETs or 6 Equivalent Gates
- -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

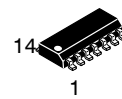
LOGIC DIAGRAM



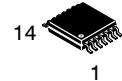
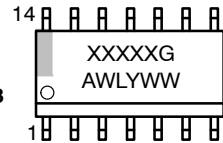
Pinout: 14-Lead Packages (Top View)



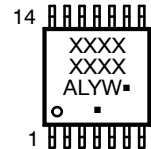
MARKING DIAGRAMS



SOIC-14 NB
D SUFFIX
CASE 751A-03



TSSOP-14
DT SUFFIX
CASE 948G



XXXX = Specific Device Code
A = Assembly Location
L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	L
L	H	L
H	L	L
H	H	H

ORDERING INFORMATION

See detailed ordering and shipping information on page 6 of this data sheet.

MC74HC08A, MC74HCT08A

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	−0.5 to +6.5	V
V_{IN}	DC Input Voltage	−0.5 to $V_{CC} + 0.5$	V
V_{OUT}	DC Output Voltage	−0.5 to $V_{CC} + 0.5$	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Current, per Pin	±25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±50	mA
I_{IK}	Input Clamp Current ($V_{IN} < 0$ or $V_{IN} > V_{CC}$)	±20	mA
I_{OK}	Output Clamp Current ($V_{OUT} < 0$ or $V_{OUT} > V_{CC}$)	±20	mA
T_{STG}	Storage Temperature	−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	±150	°C
θ_{JA}	Thermal Resistance (Note 1)	SOIC-14 NB TSSOP-14 116 150	°C/W
P_D	Power Dissipation in Still Air at 25 °C	SOIC-14 NB TSSOP-14 1077 833	mW
MSL	Moisture Sensitivity	Level 1	–
F_R	Flammability Rating	Oxygen Index: 28 to 34 UL 94 V-0 @ 0.125 in	–
V_{ESD}	ESD Withstand Voltage (Note 2)	Human Body Model Charged Device Model >2000 >1000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 76mm-by-114mm, 2-ounce copper trace no air flow per JESD51-7.

2. HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
MC74HC				
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Referenced to GND) (Note 3)	0	V_{CC}	V
T_A	Operating Free-Air Temperature	−55	+125	°C
t_r, t_f	Input Rise or Fall Time	$V_{CC} = 2.0\text{ V}$ $V_{CC} = 4.5\text{ V}$ $V_{CC} = 6.0\text{ V}$ 0 0 0	1000 500 400	ns
MC74HCT				
V_{CC}	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V_{IN}, V_{OUT}	DC Input Voltage, DC Output Voltage (Referenced to GND) (Note 3)	0	V_{CC}	V
T_A	Operating Free-Air Temperature	−55	+125	°C
t_r, t_f	Input Rise or Fall Time	0	500	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

3. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.



MC74HC08A, MC74HCT08A

DC CHARACTERISTICS (MC74HC08A)

Symbol	Parameter	Condition	V _{CC} V	Guaranteed Limit			Unit
				-55 to 25 °C	≤85 °C	≤125 °C	
V _{IH}	Minimum High-Level Input Voltage	V _{out} = 0.1V or V _{CC} - 0.1V I _{out} ≤ 20μA	2.0	1.50	1.50	1.50	V
			3.0	2.10	2.10	2.10	
			4.5	3.15	3.15	3.15	
			6.0	4.20	4.20	4.20	
V _{IL}	Maximum Low-Level Input Voltage	V _{out} = 0.1V or V _{CC} - 0.1V I _{out} ≤ 20μA	2.0	0.50	0.50	0.50	V
			3.0	0.90	0.90	0.90	
			4.5	1.35	1.35	1.35	
			6.0	1.80	1.80	1.80	
V _{OH}	Minimum High-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20μA	2.0	1.9	1.9	1.9	V
			4.5	4.4	4.4	4.4	
			6.0	5.9	5.9	5.9	
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 2.4mA I _{out} ≤ 4.0mA I _{out} ≤ 5.2mA	3.0	2.48	2.34	2.20	
			4.5	3.98	3.84	3.70	
			6.0	5.48	5.34	5.20	
V _{OL}	Maximum Low-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20μA	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
			6.0	0.1	0.1	0.1	
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 2.4mA I _{out} ≤ 4.0mA I _{out} ≤ 5.2mA	3.0	0.26	0.33	0.40	
			4.5	0.26	0.33	0.40	
			6.0	0.26	0.33	0.40	
I _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0μA	6.0	1.0	10	40	μA

AC CHARACTERISTICS (MC74HC08A)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			−55 to 25 °C	≤85 °C	≤125 °C	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, (A or B) to Y (Figures 1 and 2)	2.0	75	95	110	ns
		3.0	30	40	55	
		4.5	15	19	22	
		6.0	13	16	19	
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 2)	2.0	75	95	110	ns
		3.0	27	32	36	
		4.5	15	19	22	
		6.0	13	16	19	
C _{in}	Maximum Input Capacitance		10	10	10	pF
C _{PD}	Power Dissipation Capacitance (Per Buffer)*	Typical @ 25 °C, V _{CC} = 5.0 V, V _{EE} = 0 V				pF
		20				

* Used to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}.



MC74HC08A, MC74HCT08A

DC CHARACTERISTICS (MC74HCT08A)

Symbol	Parameter	Condition	V _{CC} V	Guaranteed Limit			Unit
				-55 to 25 °C	≤85 °C	≤125 °C	
V _{IH}	Minimum High-Level Input Voltage	V _{out} = 0.1 V or V _{CC} - 0.1 V I _{out} ≤ 20 μA	4.5 to 5.5	2.0	2.0	2.0	V
V _{IL}	Maximum Low-Level Input Voltage	V _{out} = 0.1 V or V _{CC} - 0.1 V I _{out} ≤ 20 μA	4.5 to 5.5	0.8	0.8	0.8	V
V _{OH}	Minimum High-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	4.5 5.5	4.4 5.4	4.4 5.4	4.4 5.4	V
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 4.0 mA	4.5	3.98	3.84	3.70	
V _{OL}	Maximum Low-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	4.5 5.5	0.1 0.1	0.1 0.1	0.1 0.1	V
		V _{in} = V _{IH} or V _{IL} I _{out} ≤ 4.0 mA	4.5	0.26	0.33	0.40	
I _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	5.5	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 μA	5.5	1.0	10	40	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

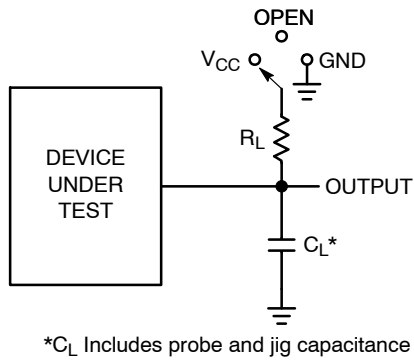
AC CHARACTERISTICS (MC74HCT08A)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit	
			−55 to 25 °C	≤85 °C	≤125 °C		
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Input A or B to Output Y (Figures 1 and 2)	t _{PLH} t _{PHL}	5.0	15 17	19 21	22 26	ns
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 2)	5.0	15	19	22		ns
C _{in}	Maximum Input Capacitance		10	10	10		pF

C _{PD}	Power Dissipation Capacitance (Per Buffer)*	Typical @ 25 °C, V _{CC} = 5.0 V, V _{EE} = 0 V	pF
		20	

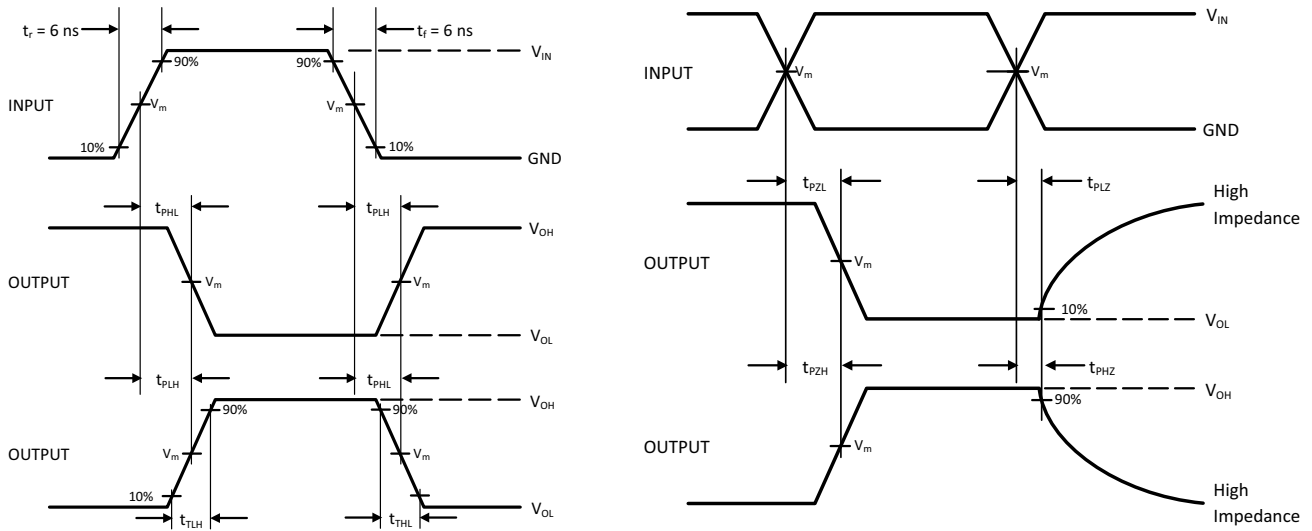
*Used to determine the no-load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}.

MC74HC08A, MC74HCT08A



Test	Switch Position	C_L	R_L
t_{PLH} / t_{PHL}	Open	50 pF	1 k Ω
t_{PLZ} / t_{PZL}	V_{CC}		
t_{PHZ} / t_{PZH}	GND		

Figure 1. Test Circuit



Device	V_{IN}, V	V_m, V
MC74HC08A	V_{CC}	$50\% \times V_{CC}$
MC74HCT08A	3 V	1.3 V

Figure 2. Switching Waveforms

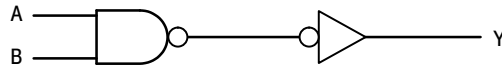


Figure 3. Expanded Logic Diagram
(1/4 of the Device)

MC74HC08A, MC74HCT08A

ORDERING INFORMATION

Device	Marking	Package	Shipping†
MC74HC08ADG	HC08AG	SOIC-14 NB	55 Units / Rail
MC74HC08ADR2G	HC08AG	SOIC-14 NB	2500 / Tape & Reel
MC74HC08ADG-Q*	HC08AG	SOIC-14 NB	2500 / Tape & Reel
MC74HC08ADR2G-Q*	HC08AG	SOIC-14 NB	2500 / Tape & Reel
MC74HC08ADTR2G	HC 08A	TSSOP-14	2500 / Tape & Reel
MC74HC08ADTR2G-Q*	HC 08A	TSSOP-14	2500 / Tape & Reel
MC74HCT08ADG	HCT08AG	SOIC-14 NB	55 Units / Rail
MC74HCT08ADR2G	HCT08AG	SOIC-14 NB	2500 / Tape & Reel
MC74HCT08ADTR2G	HCT 08	TSSOP-14	2500 / Tape & Reel
MC74HCT08ADTR2G-Q*	HCT 08	TSSOP-14	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable



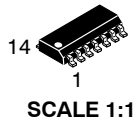
MC74HC08A, MC74HCT08A

REVISION HISTORY

Revision	Description of Changes	Date
17	Updated SOIC-14 package designation to SOIC-14 NB and revised package drawing to CASE 751A-03.	9/23/2026

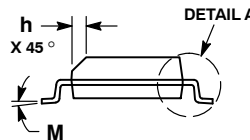
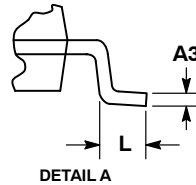
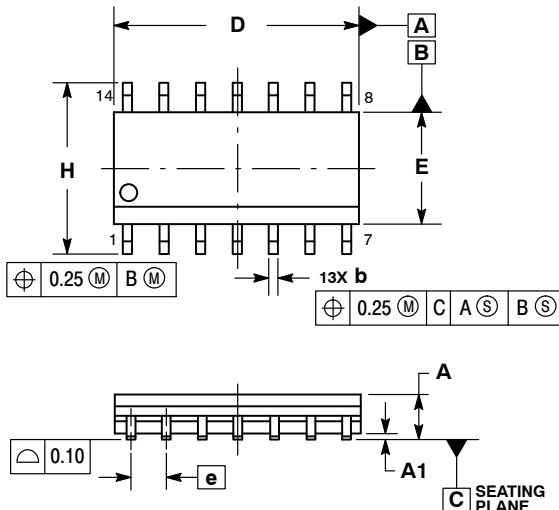
This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.





SOIC-14 NB
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

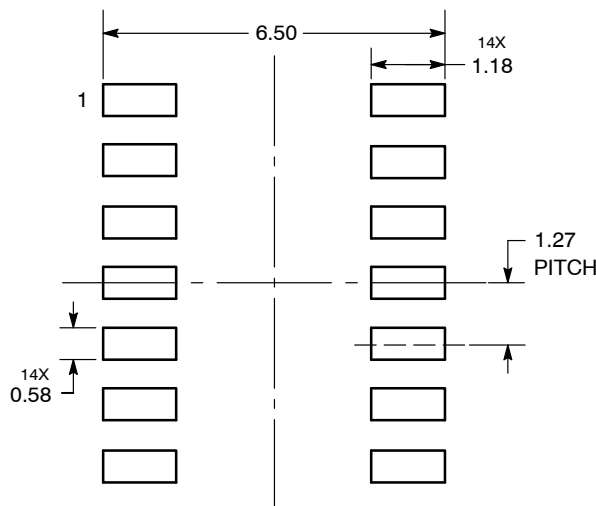


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

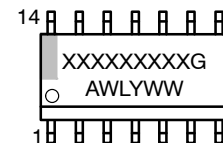
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. NO CONNECTION
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. NO CONNECTION
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 2:
CANCELLED

STYLE 3:
PIN 1. NO CONNECTION
2. ANODE
3. ANODE
4. NO CONNECTION
5. ANODE
6. NO CONNECTION
7. ANODE
8. ANODE
9. ANODE
10. NO CONNECTION
11. ANODE
12. ANODE
13. NO CONNECTION
14. COMMON CATHODE

STYLE 4:
PIN 1. NO CONNECTION
2. CATHODE
3. CATHODE
4. NO CONNECTION
5. CATHODE
6. NO CONNECTION
7. CATHODE
8. CATHODE
9. CATHODE
10. NO CONNECTION
11. CATHODE
12. CATHODE
13. NO CONNECTION
14. COMMON ANODE

STYLE 5:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. NO CONNECTION
7. COMMON ANODE
8. COMMON CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. ANODE/CATHODE
12. ANODE/CATHODE
13. NO CONNECTION
14. COMMON ANODE

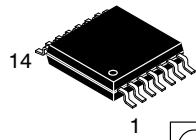
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PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. ANODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE

STYLE 7:
PIN 1. ANODE/CATHODE
2. COMMON ANODE
3. COMMON CATHODE
4. ANODE/CATHODE
5. ANODE/CATHODE
6. ANODE/CATHODE
7. ANODE/CATHODE
8. ANODE/CATHODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. COMMON CATHODE
12. COMMON ANODE
13. ANODE/CATHODE
14. ANODE/CATHODE

STYLE 8:
PIN 1. COMMON CATHODE
2. ANODE/CATHODE
3. ANODE/CATHODE
4. NO CONNECTION
5. ANODE/CATHODE
6. ANODE/CATHODE
7. COMMON ANODE
8. COMMON ANODE
9. ANODE/CATHODE
10. ANODE/CATHODE
11. NO CONNECTION
12. ANODE/CATHODE
13. ANODE/CATHODE
14. COMMON CATHODE

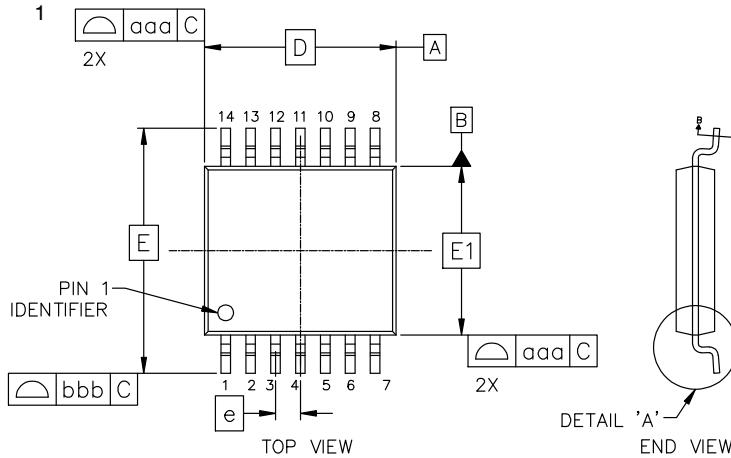
DOCUMENT NUMBER:	98ASB42565B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-14 NB	PAGE 2 OF 2

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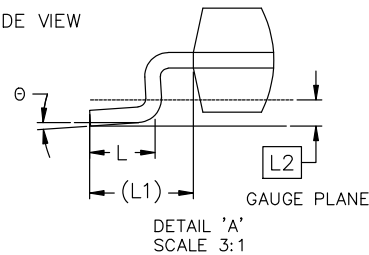
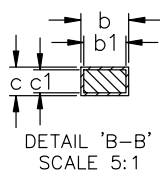
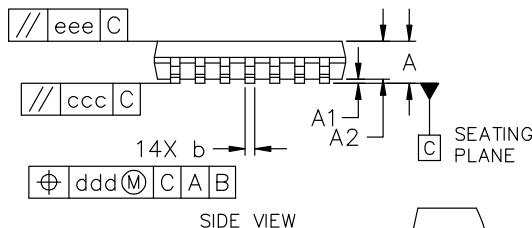


TSSOP-14 5.00x4.40x0.95, 0.65P
CASE 948G
ISSUE D

DATE 30 JUN 2026



DETAIL 'A'
 END VIEW



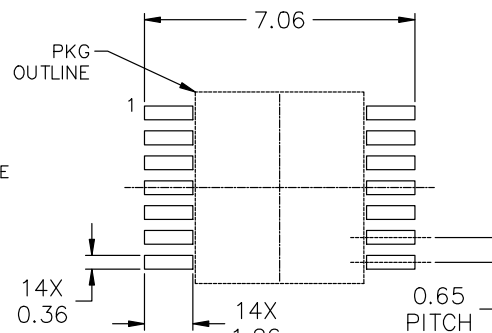
MILLIMETERS			
DIM	MIN	NOM	MAX
A	---	---	1.20
A1	0.05	0.10	0.15
A2	0.85	0.95	1.05
b	0.19	0.25	0.30
b1	0.19	0.22	0.25
c	0.09	0.15	0.20
c1	0.09	0.12	0.16
D	5.00 BSC		
E	6.40 BSC		
E1	4.40 BSC		
e	0.65 BSC		
L	0.50	0.63	0.75
L1	1.00 REF		
L2	0.25 BSC		
ø	0*	4*	8*
TOLERANCE FORM & POSITION			
aaa	0.10		
bbb	0.15		
ccc	0.08		
ddd	0.10		
eee	0.10		

NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
4. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

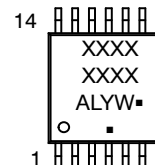
A = Assembly Location
 L = Wafer Lot
 Y = Year
 W = Work Week
 ▪ = Pb-Free Package
 (Note: Microdot may be in either location)



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



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